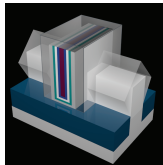


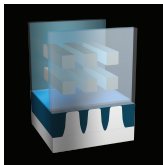
RADICALLY DIFFERENT ETCH TECHNOLOGY

The Applied Producer® Selectra® Etch System
Unprecedented Selectivity for Sustained Scaling

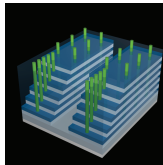
MORE COMPLEX DEVICES
INTRODUCE NEW MATERIALS



FinFET

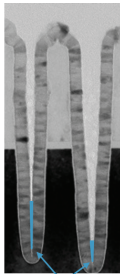


Gate All Around

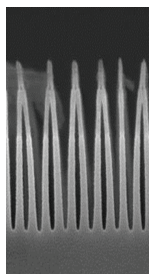


3D NAND

DIMENSIONS CHALLENGE
TRADITIONAL ETCH



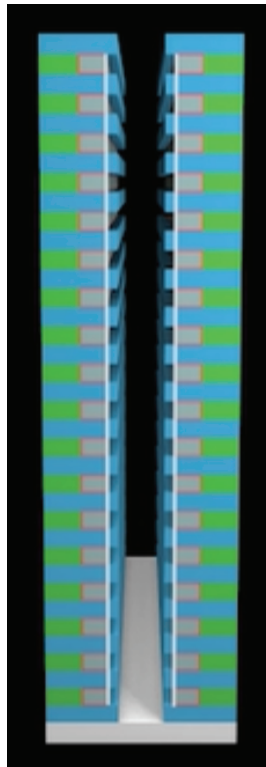
Tight Spaces



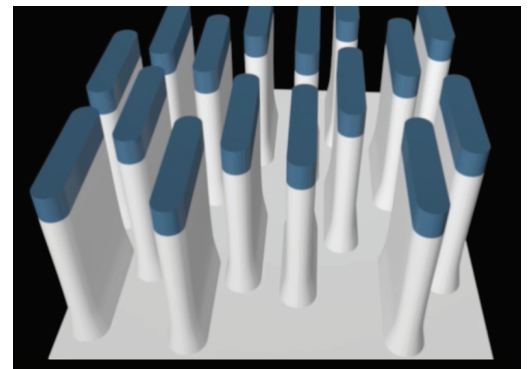
High Aspect Ratios

The industry's first extreme selectivity etch system introduces new materials engineering capabilities for future generations of self-aligned patterning schemes and 3D logic and memory devices.

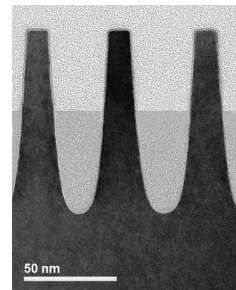
DISRUPTIVE TECHNOLOGY REQUIRED FOR
CONTINUED SCALING



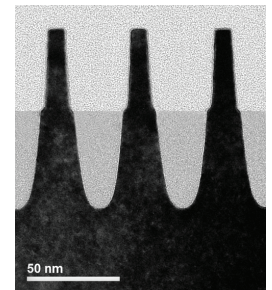
Unparalleled
Uniformity



Damage-Free Processing



Pre-Selectra



Atomic-Level Precision

Post-Selectra